

## IN THE CLAIMS

Please cancel claims 1-8 without prejudice.

Please amend claims 9 and 11.

9. (Currently Amended) An apparatus comprising:  
a polishing pad;  
a slurry disposed on said polishing pad;  
a wafer disposed on said polishing pad and said slurry; and  
a power supply adapted to apply a voltage or a current as a function of time between said polishing pad and said wafer.

11. (Currently Amended) A method comprising:  
providing a wafer, said wafer having a surface layer;  
removing said surface layer with a polishing pad;  
removing said surface layer with a slurry; and  
removing said surface layer with an electrical current as a function of time.